

CIR-W3DUMP1608G

DDR3 WIDE TEMP. DIMM 1600MHz 8GB

Description

The CIR-W3DUMP1608G is 1024M words X 64 bits, 2 ranks. Unbuffered Dual In-Line Memory Module (DIMM). DDR3L SDRAMs in Fine Ball Grid Array (FBGA) packages on a 240pin glass-epoxy substrate. Provide a high performance 8 byte interface in 133.35mm width form factor of industry standard. It is suitable for easy interchange and addition.

Specifications

Density	8GB
Pin Count	240pin
Type	Unbuffered
Dimensions	133.35mm x 30.0mm
ECC	Non-ECC
Component Config	512M x 8 bit
Data Rate	1600 MHz
CAS Latency	11
Voltage	1.35V / 1.5V
PCB Layers	6
Operating Temp.(TCASE)	-40°C~+95°C
Module Ranks	Dual Rank

Features

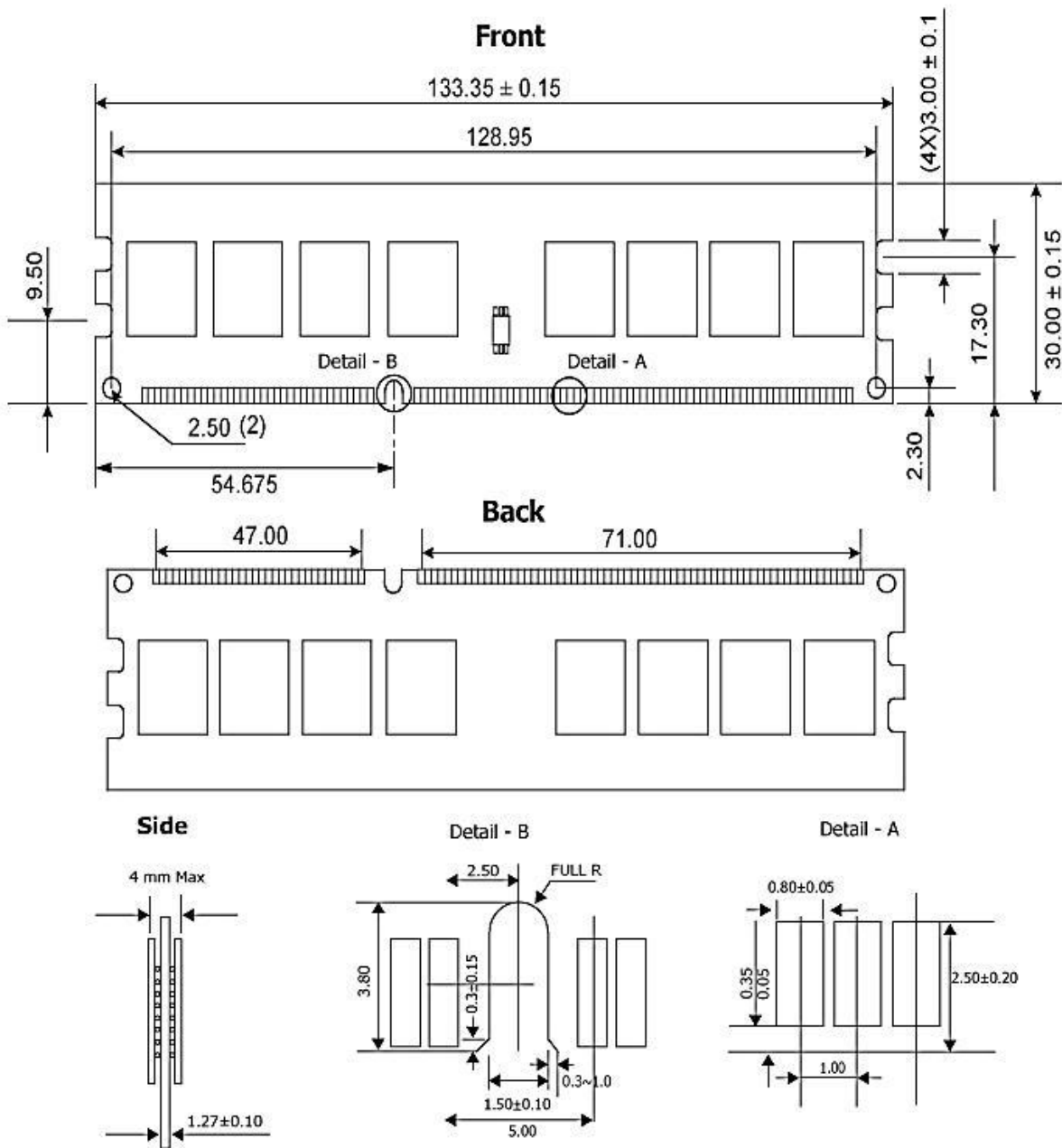
- Data rate: 1600MHz
- RoHS compliant products.
- 240pin, dual in-line memory module (DIMM)
- VDDQ= 1.35V (1.28V~1.45V) & VDDQ=1.5V(1.425V~1.575V)
- Interface: SSTL_15
- Programmable CAS Latency (CL): 6,7,8,9,10,11 support
- Fully differential clock inputs (CK, /CK) operation
- Differential Data Strobe (DQS, /DQS)
- Serial presence detect with EEPROM
- 8 independent internal bank
- 8K refresh cycles /64ms
- On Die Termination supported
- Asynchronous RESET pin supported
- ZQ calibration supported
- POSTED CAS additive latency (AL)
- Bi-directional Differential Data Strobe
- Burst Length: 4, 8
- 8 bit pre-fetch
- Support Industrial Temp (-40 ~95°C)
 - tREFI 7.8us at -40 °C ≤ TCASE ≤ 85°C
 - tREFI 3.9us at 85 °C < TCASE ≤ 95°C

Speed Grade

Frequency Grade	Data Transfer Rate	CAS Latency Support						CL-tRCD-tRP
		CL6	CL7	CL8	CL9	CL10	CL11	
DDR3-1600	PC3-12800	800	1066	1066	1333	1333	1600	11-11-11

Package Dimensions

Unit: mm



Tolerances : $\pm 0.15\text{mm}$ unless otherwise specified